



# 1SV267 — Silicon Epitaxial Type PIN Diode for VHF, UHF, AGC Applications

## Features

- Series connection of 2 elements in a very small sized package facilitates high-density mounting and permits 1SV267-applied equipment to be made smaller
- Small interterminal capacitance (C=0.23pF typ)
- Small forward series resistance (rs=2.5Ω typ)

## Specifications

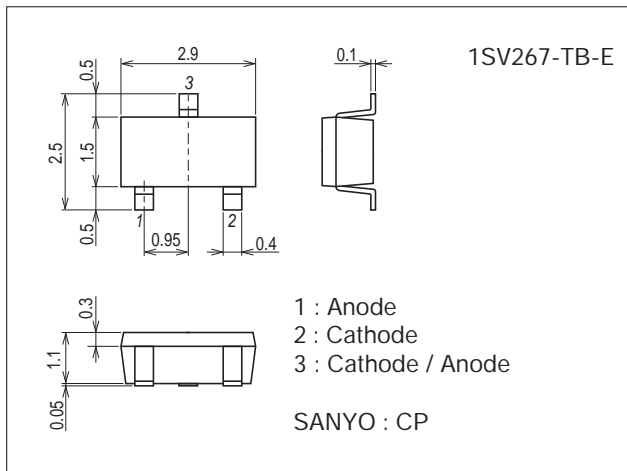
Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Conditions	Ratings	Unit
Reverse Voltage	V <sub>R</sub>		50	V
Forward Current	I <sub>F</sub>		50	mA
Allowable Power Dissipation	P		150	mW
Junction Temperature	T <sub>j</sub>		125	°C
Storage Temperature	T <sub>stg</sub>		-55 to +125	°C

## Package Dimensions

unit : mm (typ)

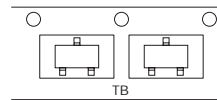
7013A-008



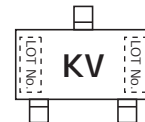
## Product & Package Information

- Package : CP
- JEITA, JEDEC : SC-59, TO-236, SOT-23, TO-236AB
- Minimum Packing Quantity : 3,000 pcs./reel

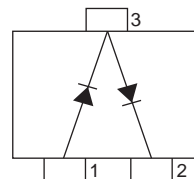
## Packing Type: TB



## Marking



## Electrical Connection



# 1SV267

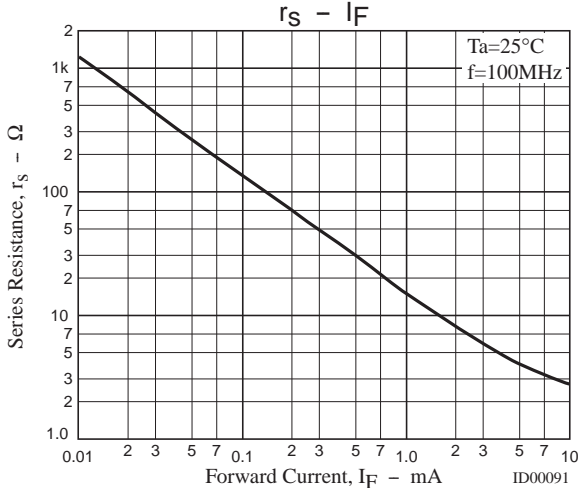
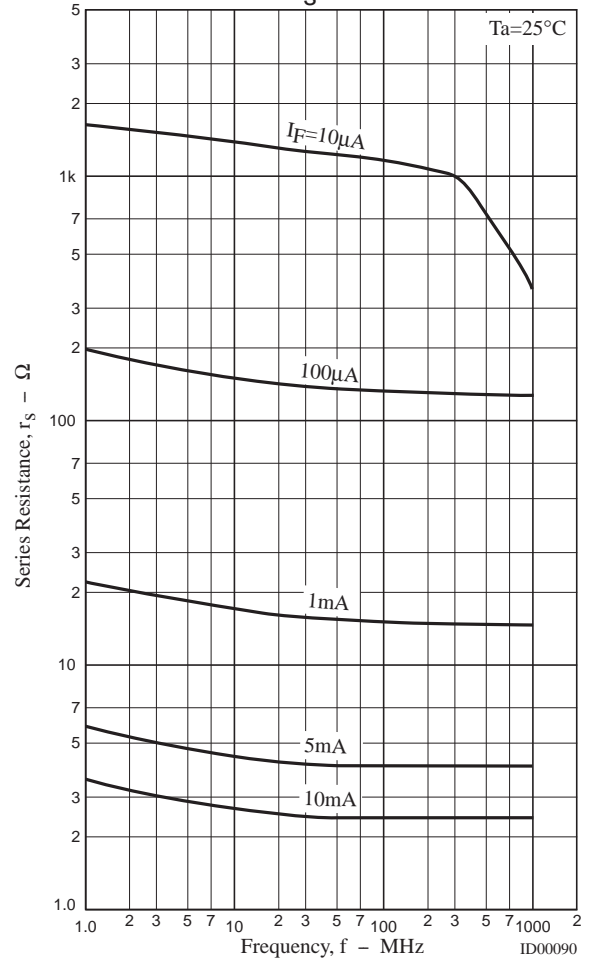
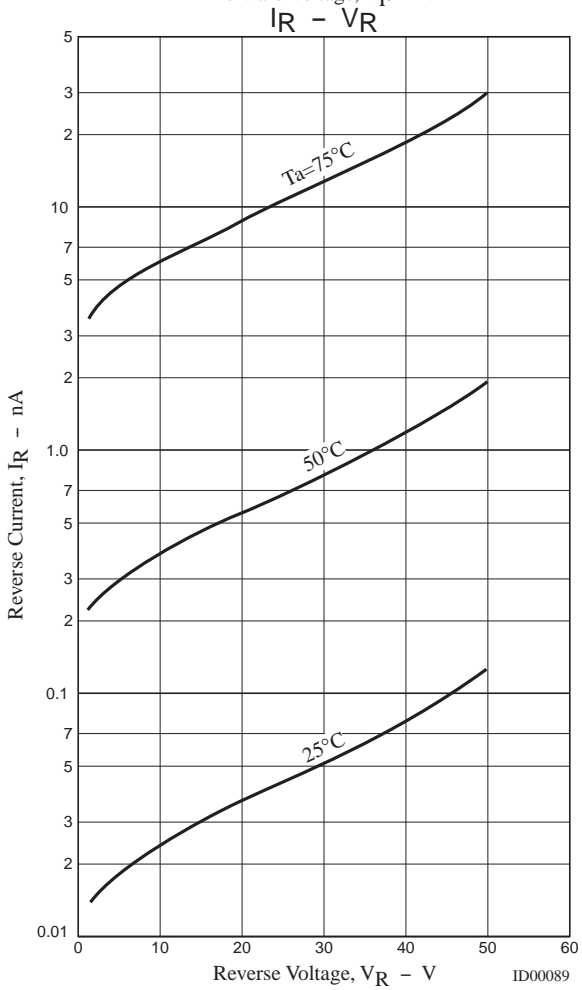
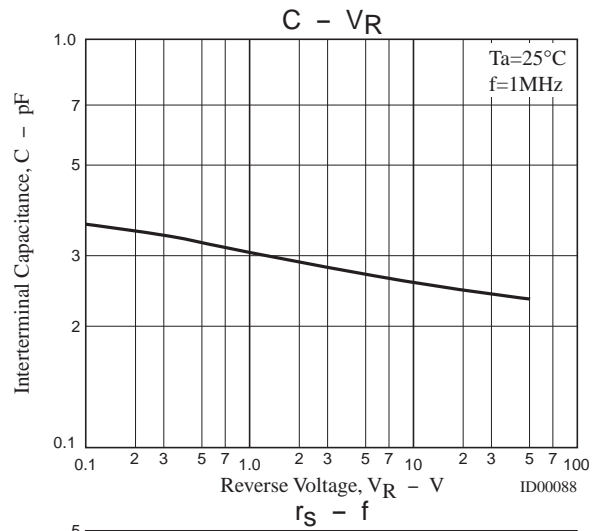
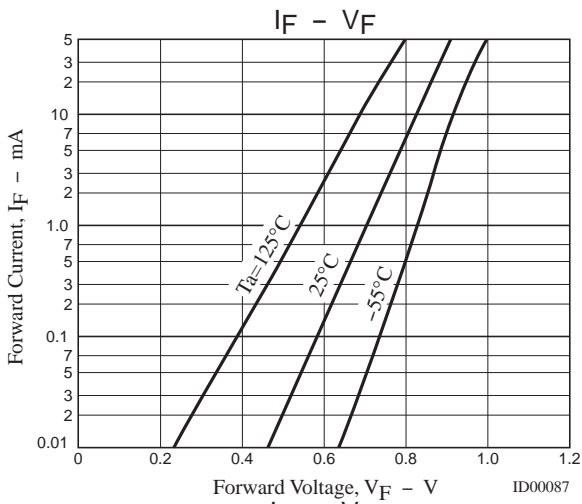
## Electrical Characteristics at Ta=25°C

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Reverse Voltage	V <sub>R</sub>	I <sub>R</sub> =10μA	50			V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =50V			0.1	μA
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =50mA		0.91		V
Interterminal Capacitance	C	V <sub>R</sub> =50V, f=1MHz		0.23		pF
Series Resistance	r <sub>s</sub>	I <sub>F</sub> =5mA, f=100MHz		4.0		Ω
		I <sub>F</sub> =10mA, f=100MHz		2.5		Ω

Note : The specifications shown above are for each individual diode.

## Ordering Information

Device	Package	Shipping	memo
1SV267-TB-E	CP	3,000pcs./reel	Pb Free



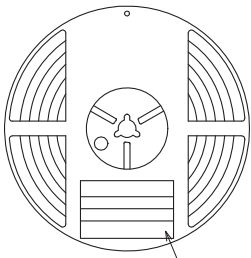
Embossed Taping Specification

1SV267-TB-E

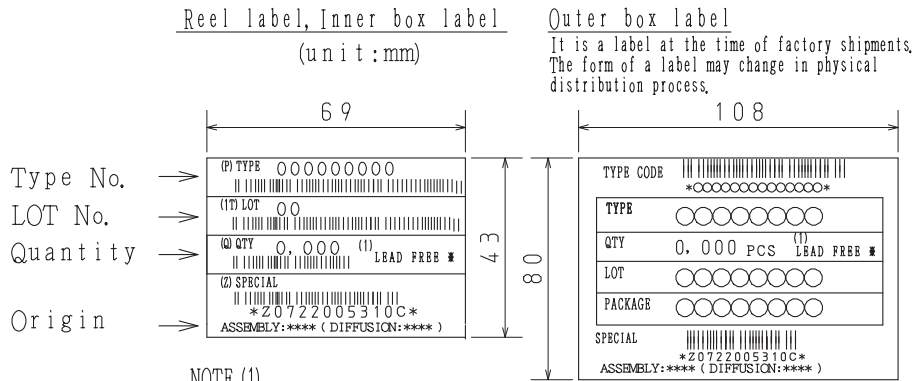
1. Packing Format

Package Name	Carrier Tape Type	Maximum Number of devices contained (pcs)			Packing format	
		Reel	Inner box	Outer box	Inner BOX (C-1)	Outer BOX (A-7)
CP	CP	3,000	15,000	90,000	5 reels contained Dimensions:mm (external) 183×72×185	6 inner boxes contained Dimensions:mm (external) 440×195×210

Packing method



Reel label



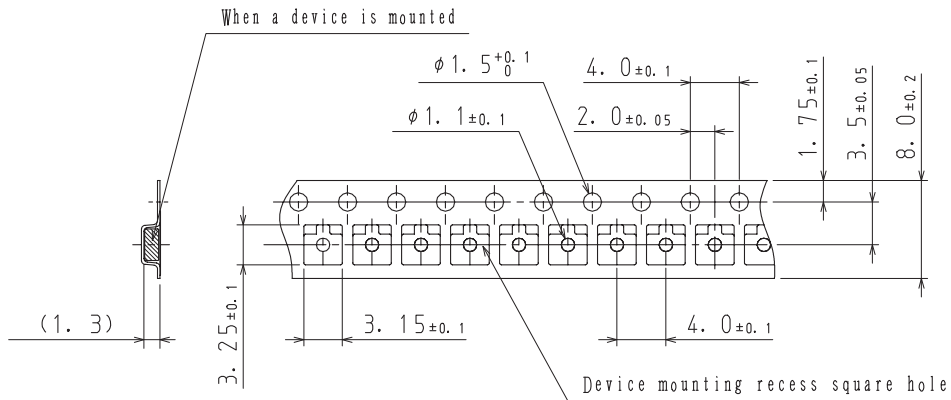
NOTE (1)

The LEAD FREE \* description shows that the surface treatment of the terminal is lead free.

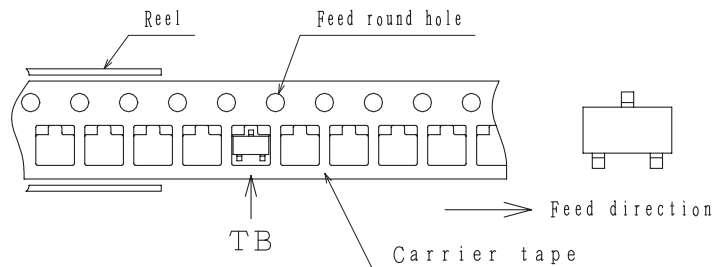
Label	JEITA Phase
LEAD FREE 3	JEITA Phase 3A
LEAD FREE 4	JEITA Phase 3

2. Taping configuration

2-1. Carrier tape size (unit:mm)



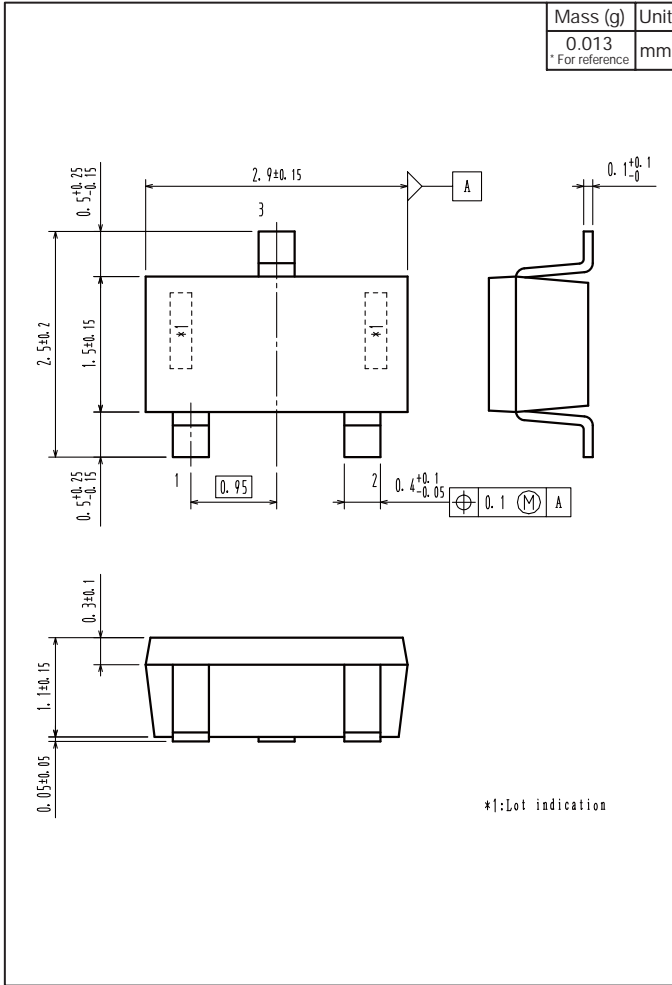
2-2. Device placement direction



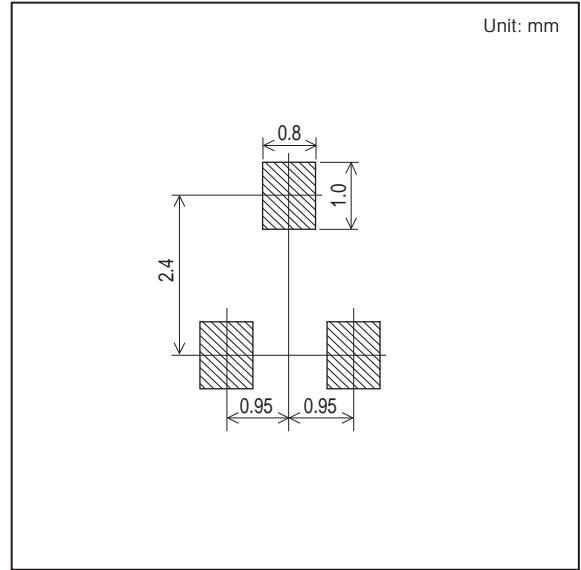
Those with one electrode terminal on the feed hole side.....TB

Outline Drawing

1SV267-TB-E



Land Pattern Example



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